

June 1998

### Features

- This Circuit is Processed in Accordance to MIL-STD-883 and is Fully Conformant Under the Provisions of Paragraph 1.2.1.
- High Slew Rate..... 14V/ $\mu$ s (Min)
- Wide Gain Bandwidth ( $A_V \geq 5$ ) ..... 60MHz (Min)
- Low Noise (at 1kHz)..... 4.5nV/ $\sqrt{\text{Hz}}$  (Max)
- Low Offset Voltage.....100 $\mu$ V (Max)
- Low Offset Drift With Temperature. . . . 1.8 $\mu$ V/ $^{\circ}$ C (Max)
- High CMRR.....100dB (Min)
- High Voltage Gain ..... 700kV/V (Min)

### Applications

- High Speed Signal Conditioners
- Wide Bandwidth Instrumentation Amplifiers
- Low Level Transducer Amplifiers
- Fast, Low Level Voltage Comparators
- Highest Quality Audio Preamplifiers
- Pulse/RF Amplifiers

### Description

The HA-5137/883 monolithic operational amplifier features an excellent combination of precision DC and wideband high speed characteristics. Utilizing the Intersil DI technology and advanced processing techniques, this unique design unites low noise precision instrumentation performance with high speed, wideband capability.

This amplifier's impressive list of features include low  $V_{OS}$ , wide gain-bandwidth, high open loop gain, and high CMRR. Additionally, this flexible device operates over a wide supply range while consuming only 120mW of power.

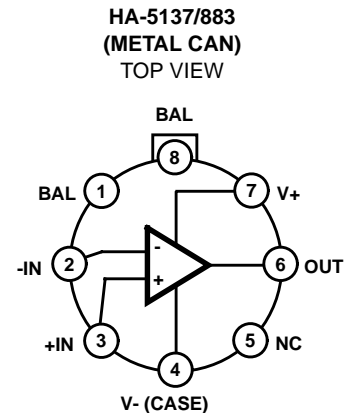
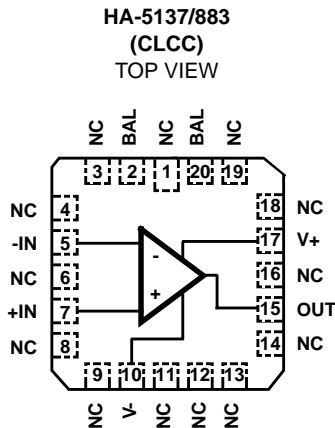
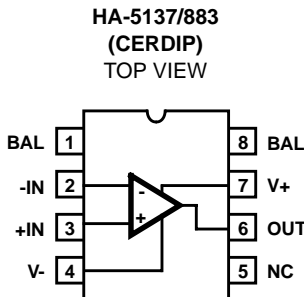
Using the HA-5137/883 allows designers to minimize errors while maximizing speed and bandwidth in applications requiring gains greater than five.

This device is ideally suited for low level transducer signal amplifier circuits. Other applications which can utilize the HA-5137/883's qualities include instrumentation amplifiers, pulse or RF amplifiers, audio preamplifiers, and signal conditioning circuits.

### Ordering Information

PART NUMBER	TEMP. RANGE ( $^{\circ}$ C)	PACKAGE	PKG. NO.
HA2-5137/883	-55 to 125	8 Pin Metal Can	T8.C
HA4-5137/883	-55 to 125	20 Ld CLCC	J20.A
HA7-5137/883	-55 to 125	8 Ld CERDIP	F8.3A

### Pinouts



**Absolute Maximum Ratings**

Voltage Between V+ and V- Terminals .....	44V
Differential Input Voltage (Note 1).....	0.7V
Voltage at Either Input Terminal .....	V+ to V-
Input Current .....	25mA
Output Current .....	Full Short Circuit Protection
ESD Rating.....	<2000V

**Operating Conditions**

Temperature Range .....	-55°C to 125°C
Supply Voltage Range .....	± 15V
V <sub>INCM</sub> ≤ 1/2 (V+ - V-)	
R <sub>L</sub> ≥ 600Ω	

**Thermal Information**

Thermal Resistance (Typical, Note 2)	θ <sub>JA</sub> (°C/W)	θ <sub>JC</sub> (°C/W)
CERDIP Package .....	115	28
CLCC Package .....	85	26
Metal Can Package .....	155	67
Package Power Dissipation Limit at 75°C for T <sub>J</sub> ≤ 175°C		
CERDIP Package .....	870mW	
CLCC Package .....	1.18W	
Metal Can Package .....	645mW	
Package Power Dissipation Derating Factor Above 75°C		
CERDIP Package .....	8.7mW/°C	
CLCC Package .....	11.8mW/°C	
Metal Can Package .....	6.5mW/°C	
Maximum Junction Temperature (T <sub>J</sub> ) .....	175°C	
Maximum Storage Temperature Range .....	-65°C to 150°C	
Maximum Lead Temperature (Soldering 10s) .....	300°C	

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTES:

1. For differential input voltages greater than 0.7V, the input current must be limited to 25mA to protect the back-to-back input diodes.
2. θ<sub>JA</sub> is measured with the component mounted on an evaluation PC board in free air.

**TABLE 1. DC ELECTRICAL PERFORMANCE SPECIFICATIONS**

Device Tested at: V<sub>SUPPLY</sub> = ±15V, R<sub>SOURCE</sub> = 50Ω, R<sub>LOAD</sub> = 100kΩ, V<sub>OUT</sub> = 0V, Unless Otherwise Specified.

PARAMETER	SYMBOL	CONDITIONS	GROUP A SUBGROUPS	TEMP. (°C)	MIN	MAX	UNITS
Input Offset Voltage	V <sub>IO</sub>	V <sub>CM</sub> = 0V	1	25	-100	100	μV
			2, 3	125, -55	-300	300	μV
Input Bias Current	I <sub>B</sub>	V <sub>CM</sub> = 0V, R <sub>S</sub> = 10kΩ, 50Ω  $\left(\frac{ I_{B+}  +  I_{B-} }{2}\right)$	1	25	-	80	nA
			2, 3	125, -55	-	150	nA
Input Offset Current	I <sub>IO</sub>	V <sub>CM</sub> = 0V, +R <sub>S</sub> = 10kΩ, -R <sub>S</sub> = 10kΩ	1	25	-75	75	nA
			2, 3	125, -55	-135	135	nA
Common Mode Range	+CMR	V+ = +4.7V, V- = -25.3V	1	25	10.3	-	V
			2, 3	125, -55	10.3	-	V
	-CMR	V+ = 25.3V, V- = -4.7V	1	25	-	-10.3	V
			2, 3	125, -55	-	-10.3	V
Large Signal Voltage Gain	+A <sub>VOL</sub>	V <sub>OUT</sub> = 0V and +10V, R <sub>L</sub> = 2kΩ	4	25	700	-	kV/V
			5, 6	125, -55	300	-	kV/V
	-A <sub>VOL</sub>	V <sub>OUT</sub> = 0V and -10V, R <sub>L</sub> = 2kΩ	4	25	700	-	kV/V
			5, 6	125, -55	300	-	kV/V
Common Mode Rejection Ratio	+CMRR	ΔV <sub>CM</sub> = +11V	1	25	100	-	dB
		ΔV <sub>CM</sub> = +10V	2, 3	125, -55	100	-	dB
	-CMRR	ΔV <sub>CM</sub> = -11V	1	25	100	-	dB
		ΔV <sub>CM</sub> = -10V	2, 3	125, -55	100	-	dB

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**TABLE 1. DC ELECTRICAL PERFORMANCE SPECIFICATIONS (Continued)**

Device Tested at:  $V_{SUPPLY} = \pm 15V$ ,  $R_{SOURCE} = 50\Omega$ ,  $R_{LOAD} = 100k\Omega$ ,  $V_{OUT} = 0V$ , Unless Otherwise Specified.

PARAMETER	SYMBOL	CONDITIONS	GROUP A SUBGROUPS	TEMP. (°C)	MIN	MAX	UNITS
Output Voltage Swing	+V <sub>OUT1</sub>	R <sub>L</sub> = 2kΩ	4	25	11.5	-	V
			5, 6	125, -55	11.5	-	V
	-V <sub>OUT1</sub>	R <sub>L</sub> = 2kΩ	4	25	-	-11.5	V
			5, 6	125, -55	-	-11.5	V
	+V <sub>OUT2</sub>	R <sub>L</sub> = 600Ω	4	25	10	-	V
-V <sub>OUT2</sub>	R <sub>L</sub> = 600Ω	4	25	-	-10	V	
Output Current	+I <sub>OUT</sub>	V <sub>OUT</sub> = -10V	4	25	16.5	-	mA
	-I <sub>OUT</sub>	V <sub>OUT</sub> = +10V	4	25	-	-16.5	mA
Quiescent Power Supply Current	+I <sub>CC</sub>	V <sub>OUT</sub> = 0V, I <sub>OUT</sub> = 0mA	1	25	-	4	mA
			2, 3	125, -55	-	4	mA
	-I <sub>CC</sub>	V <sub>OUT</sub> = 0V, I <sub>OUT</sub> = 0mA	1	25	-4	-	mA
			2, 3	125, -55	-4	-	mA
Power Supply Rejection Ratio	+PSRR	$\Delta V_{SUP} = 14V$ , V <sub>+</sub> = +4V, V <sub>-</sub> = -15V, V <sub>+</sub> = +18V, V <sub>-</sub> = -15V	1	25	86	-	dB
			2, 3	125, -55	86	-	dB
	-PSRR	$\Delta V_{SUP} = 14V$ , V <sub>+</sub> = +15V, V <sub>-</sub> = -4V, V <sub>+</sub> = +15V, V <sub>-</sub> = -18V	1	25	86	-	dB
			2, 3	125, -55	86	-	dB
Offset Voltage Adjustment	+V <sub>IOAdj</sub>	Note 3	1	25	V <sub>IO-1</sub>	-	mV
			2, 3	125, -55	V <sub>IO-1</sub>	-	mV
	-V <sub>IOAdj</sub>	Note 3	1	25	V <sub>IO+1</sub>	-	mV
			2, 3	125, -55	V <sub>IO+1</sub>	-	mV

NOTE:

- Offset adjustment range is [V<sub>IO</sub> (Measured) ±1mV] minimum referred to output. This test is for functionality only to assure adjustment through 0V.

**TABLE 2. AC ELECTRICAL PERFORMANCE SPECIFICATIONS**

Device Tested at:  $V_{SUPPLY} = \pm 15V$ ,  $R_{SOURCE} = 50\Omega$ ,  $R_{LOAD} = 2k\Omega$ ,  $C_{LOAD} = 50pF$ ,  $A_{VCL} = +10V/V$ , Unless Otherwise Specified.

PARAMETER	SYMBOL	CONDITIONS	GROUP A SUBGROUPS	TEMP. (°C)	MIN	MAX	UNITS
Slew Rate	+SR	V <sub>OUT</sub> = -3V to +3V	7	25	14	-	V/μs
	-SR	V <sub>OUT</sub> = +3V to -3V	7	25	14	-	V/μs
Rise and Fall Time	t <sub>r</sub>	V <sub>OUT</sub> = 0 to +200mV 10% ≤ t <sub>r</sub> ≤ 90%	7	25	-	100	ns
	t <sub>f</sub>	V <sub>OUT</sub> = 0 to -200mV 10% ≤ t <sub>f</sub> ≤ 90%	7	25	-	100	ns
Overshoot	+OS	V <sub>OUT</sub> = 0 to +200mV	7	25	-	40	%
	-OS	V <sub>OUT</sub> = 0 to -200mV	7	25	-	40	%

**TABLE 3. ELECTRICAL PERFORMANCE SPECIFICATIONS**

Device Characterized at:  $V_{SUPPLY} = \pm 15V$ ,  $R_{LOAD} = 2k\Omega$ ,  $C_{LOAD} = 50pF$ ,  $A_V = +5V/V$ , Unless Otherwise Specified.

PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMP. (°C)	MIN	MAX	UNITS
Average Offset Voltage Drift	$V_{IO TC}$	$V_{CM} = 0V$	4	-55 to 125	-	1.8	$\mu V/^\circ C$
Differential Input Resistance	$R_{IN}$	$V_{CM} = 0V$	4	25	0.8	-	$M\Omega$
Low Frequency Peak-to-Peak Noise	$E_{NP-P}$	0.1Hz to 10Hz	4	25	-	0.25	$\mu V_{P-P}$
Input Noise Voltage Density	$E_N$	$R_S = 20\Omega$ , $f_O = 10Hz$	4	25	-	10	$nV/\sqrt{Hz}$
		$R_S = 20\Omega$ , $f_O = 100Hz$	4	25	-	5.6	$nV/\sqrt{Hz}$
		$R_S = 20\Omega$ , $f_O = 1kHz$	4	25	-	4.5	$nV/\sqrt{Hz}$
Input Noise Current Density	$I_N$	$R_S = 2M\Omega$ , $f_O = 10Hz$	4	25	-	4.0	$pA/\sqrt{Hz}$
		$R_S = 2M\Omega$ , $f_O = 100Hz$	4	25	-	2.3	$pA/\sqrt{Hz}$
		$R_S = 2M\Omega$ , $f_O = 1kHz$	4	25	-	0.6	$pA/\sqrt{Hz}$
Gain Bandwidth Product	GBWP	$V_O = 100mV$ , $f_O = 10kHz$	4	25	60	-	MHz
		$V_O = 100mV$ , $f_O = 1MHz$	4	25	43	-	MHz
Full Power Bandwidth	FPBW	$V_{PEAK} = 10V$	4, 5	25	220	-	kHz
Minimum Closed Loop Stable Gain	CLSG	$R_L = 2k\Omega$ , $C_L = 50pF$	4	-55 to 125	$\pm 5$	-	V/V
Settling Time	$t_S$	To 0.1% for a 10V Step	4	25	-	1.5	$\mu s$
Output Resistance	$R_{OUT}$	Open Loop	4	25	-	100	$\Omega$
Quiescent Power Consumption	PC	$V_{OUT} = 0V$ , $I_{OUT} = 0mA$	4, 6	-55 to 125	-	120	mW

NOTES:

- Parameters listed in Table 3 are controlled via design or process parameters and are not directly tested at final production. These parameters are lab characterized upon initial design release, or upon design changes. These parameters are guaranteed by characterization based upon data from multiple production runs which reflect lot to lot and within lot variation.
- Full Power Bandwidth guarantee based on Slew Rate measurement using  $FPBW = Slew\ Rate / (2\pi V_{PEAK})$ .
- Quiescent Power Consumption based upon Quiescent Supply Current test maximum. (No load on output.)

**TABLE 4. ELECTRICAL TEST REQUIREMENTS**

MIL-STD-883 TEST REQUIREMENTS	SUBGROUPS (SEE TABLES 1 AND 2)
Interim Electrical Parameters (Pre Burn-In)	1
Final Electrical Test Parameters	1 (Note 7), 2, 3, 4, 5, 6, 7
Group A Test Requirements	1, 2, 3, 4, 5, 6, 7
Groups C and D Endpoints	1

NOTE:

- PDA applies to Subgroup 1 only.

**Die Characteristics**

**DIE DIMENSIONS:**

104.3 x 65 x 19 mils  
2650 x 1650 x 483µm

**METALLIZATION:**

Type: Al, 1% Cu  
Thickness: 16kÅ ± 2kÅ

**GLASSIVATION:**

Type: Nitride (Si<sub>3</sub>N<sub>4</sub>) over Silox (SiO<sub>2</sub>, 5% Phos.)  
Silox Thickness: 12kÅ ± 2kÅ  
Nitride Thickness: 3.5kÅ ± 1.5kÅ

**WORST CASE CURRENT DENSITY:**

3.6 x 10<sup>5</sup> A/cm<sup>2</sup> at 15mA  
This device meets Glassivation Integrity Test Requirement per MIL-STD-883 Method 2021 and MIL-I-38535 Paragraph 30.5.5.4.

**SUBSTRATE POTENTIAL (Powered Up):**

V-

**TRANSISTOR COUNT:**

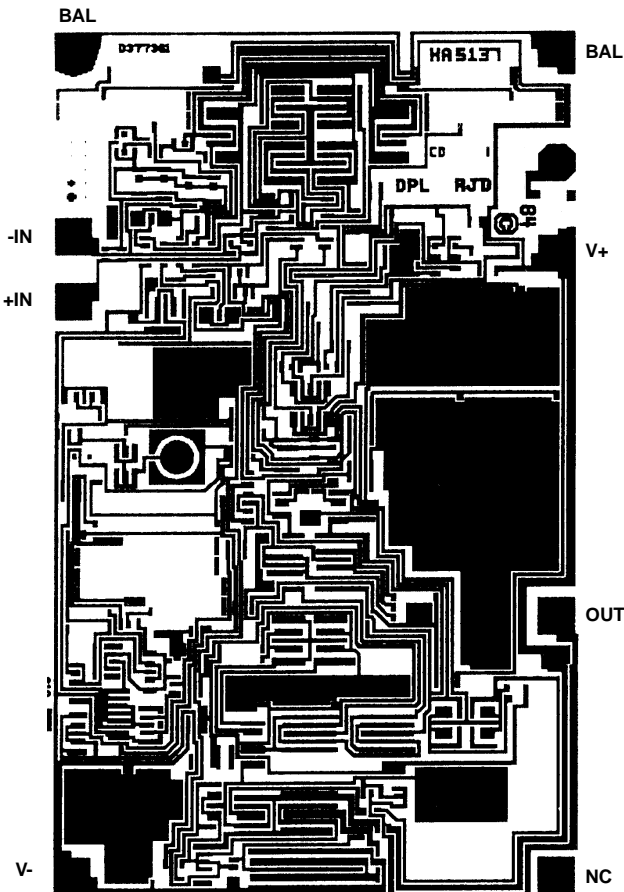
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**PROCESS:**

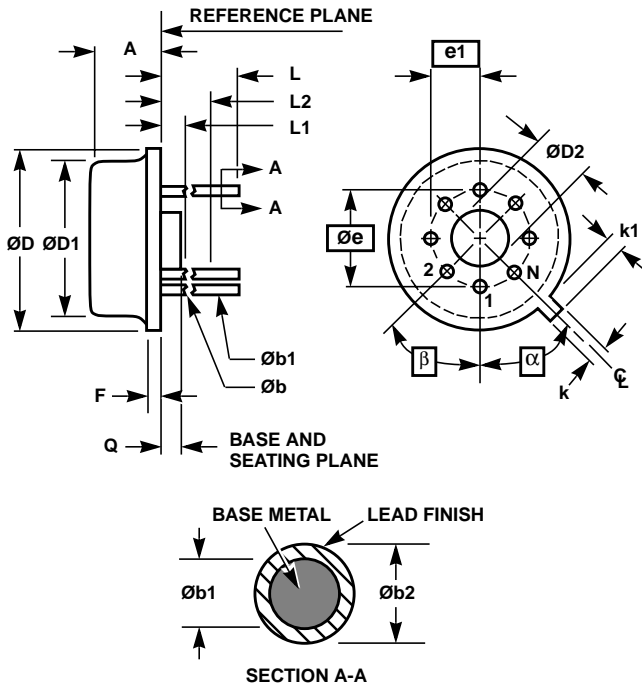
Bipolar Dielectric Isolation

**Metallization Mask Layout**

HA-5137/883



**Metal Can Packages (Can)**



**NOTES:**

1. (All leads)  $\varnothing b$  applies between L1 and L2.  $\varnothing b1$  applies between L2 and 0.500 from the reference plane. Diameter is uncontrolled in L1 and beyond 0.500 from the reference plane.
2. Measured from maximum diameter of the product.
3.  $\alpha$  is the basic spacing from the centerline of the tab to terminal 1 and  $\beta$  is the basic spacing of each lead or lead position (N - 1 places) from  $\alpha$ , looking at the bottom of the package.
4. N is the maximum number of terminal positions.
5. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
6. Controlling dimension: INCH.

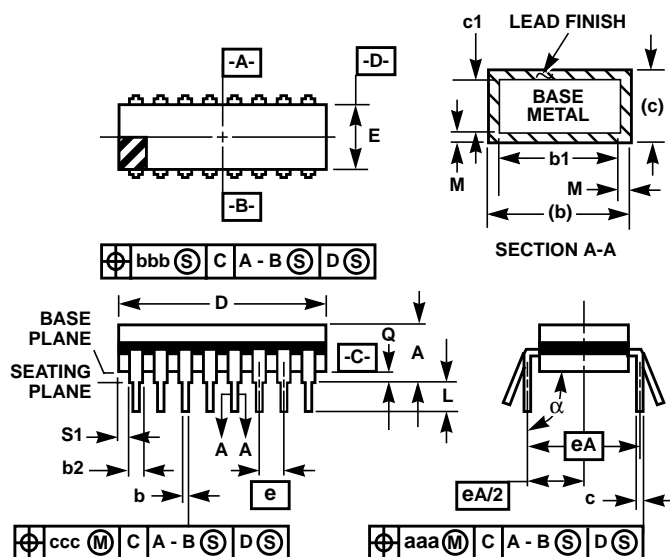
**T8.C MIL-STD-1835 MACY1-X8 (A1)  
8 LEAD METAL CAN PACKAGE**

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.165	0.185	4.19	4.70	-
$\varnothing b$	0.016	0.019	0.41	0.48	1
$\varnothing b1$	0.016	0.021	0.41	0.53	1
$\varnothing b2$	0.016	0.024	0.41	0.61	-
$\varnothing D$	0.335	0.375	8.51	9.40	-
$\varnothing D1$	0.305	0.335	7.75	8.51	-
$\varnothing D2$	0.110	0.160	2.79	4.06	-
e	0.200 BSC		5.08 BSC		-
e1	0.100 BSC		2.54 BSC		-
F	-	0.040	-	1.02	-
k	0.027	0.034	0.69	0.86	-
k1	0.027	0.045	0.69	1.14	2
L	0.500	0.750	12.70	19.05	1
L1	-	0.050	-	1.27	1
L2	0.250	-	6.35	-	1
Q	0.010	0.045	0.25	1.14	-
$\alpha$	45° BSC		45° BSC		3
$\beta$	45° BSC		45° BSC		3
N	8		8		4

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**Ceramic Dual-In-Line Frit Seal Packages (CERDIP)**

**F8.3A MIL-STD-1835 GDIP1-T8 (D-4, CONFIGURATION A)  
8 LEAD CERAMIC DUAL-IN-LINE FRIT SEAL PACKAGE**



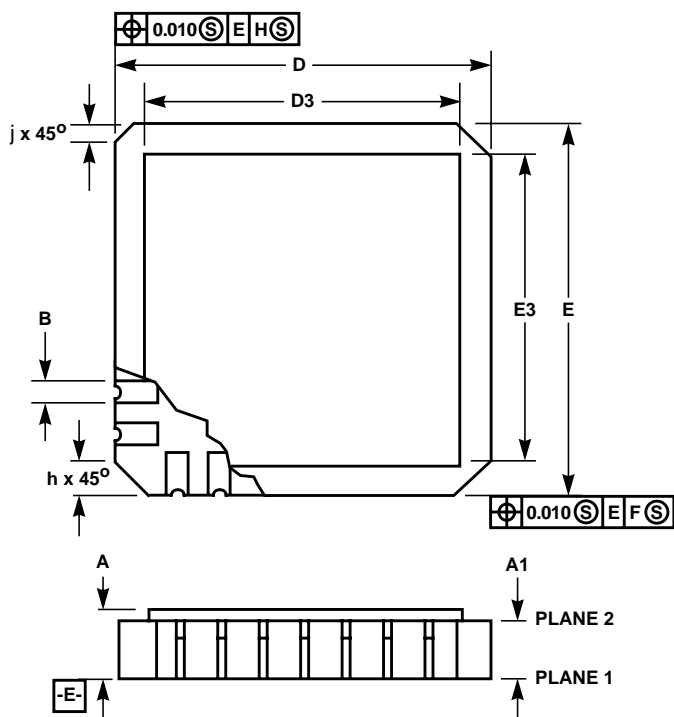
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.200	-	5.08	-
b	0.014	0.026	0.36	0.66	2
b1	0.014	0.023	0.36	0.58	3
b2	0.045	0.065	1.14	1.65	-
b3	0.023	0.045	0.58	1.14	4
c	0.008	0.018	0.20	0.46	2
c1	0.008	0.015	0.20	0.38	3
D	-	0.405	-	10.29	5
E	0.220	0.310	5.59	7.87	5
e	0.100 BSC		2.54 BSC		-
eA	0.300 BSC		7.62 BSC		-
eA/2	0.150 BSC		3.81 BSC		-
L	0.125	0.200	3.18	5.08	-
Q	0.015	0.060	0.38	1.52	6
S1	0.005	-	0.13	-	7
$\alpha$	90°	105°	90°	105°	-
aaa	-	0.015	-	0.38	-
bbb	-	0.030	-	0.76	-
ccc	-	0.010	-	0.25	-
M	-	0.0015	-	0.038	2, 3
N	8		8		8

**NOTES:**

1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.
2. The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
3. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness.
4. Corner leads (1, N, N/2, and N/2+1) may be configured with a partial lead paddle. For this configuration dimension b3 replaces dimension b2.
5. This dimension allows for off-center lid, meniscus, and glass overrun.
6. Dimension Q shall be measured from the seating plane to the base plane.
7. Measure dimension S1 at all four corners.
8. N is the maximum number of terminal positions.
9. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
10. Controlling dimension: INCH

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**Ceramic Leadless Chip Carrier Packages (CLCC)**



**J20.A MIL-STD-1835 CQCC1-N20 (C-2)  
20 PAD CERAMIC LEADLESS CHIP CARRIER PACKAGE**

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.060	0.100	1.52	2.54	6, 7
A1	0.050	0.088	1.27	2.23	-
B	-	-	-	-	-
B1	0.022	0.028	0.56	0.71	2, 4
B2	0.072 REF		1.83 REF		-
B3	0.006	0.022	0.15	0.56	-
D	0.342	0.358	8.69	9.09	-
D1	0.200 BSC		5.08 BSC		-
D2	0.100 BSC		2.54 BSC		-
D3	-	0.358	-	9.09	2
E	0.342	0.358	8.69	9.09	-
E1	0.200 BSC		5.08 BSC		-
E2	0.100 BSC		2.54 BSC		-
E3	-	0.358	-	9.09	2
e	0.050 BSC		1.27 BSC		-
e1	0.015	-	0.38	-	2
h	0.040 REF		1.02 REF		5
j	0.020 REF		0.51 REF		5
L	0.045	0.055	1.14	1.40	-
L1	0.045	0.055	1.14	1.40	-
L2	0.075	0.095	1.91	2.41	-
L3	0.003	0.015	0.08	0.38	-
ND	5		5		3
NE	5		5		3
N	20		20		3

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**NOTES:**

1. Metallized castellations shall be connected to plane 1 terminals and extend toward plane 2 across at least two layers of ceramic or completely across all of the ceramic layers to make electrical connection with the optional plane 2 terminals.
2. Unless otherwise specified, a minimum clearance of 0.015 inch (0.38mm) shall be maintained between all metallized features (e.g., lid, castellations, terminals, thermal pads, etc.)
3. Symbol "N" is the maximum number of terminals. Symbols "ND" and "NE" are the number of terminals along the sides of length "D" and "E", respectively.
4. The required plane 1 terminals and optional plane 2 terminals (if used) shall be electrically connected.
5. The corner shape (square, notch, radius, etc.) may vary at the manufacturer's option, from that shown on the drawing.
6. Chip carriers shall be constructed of a minimum of two ceramic layers.
7. Dimension "A" controls the overall package thickness. The maximum "A" dimension is package height before being solder dipped.
8. Dimensioning and tolerancing per ANSI Y14.5M-1982.
9. Controlling dimension: INCH.

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